

Amendments to the Specification:

Applicant proposes to amend the specification by replacing paragraph [0031] with the following paragraph, which is marked to show proposed amendments:

[0031] A fourth embodiment of the present invention is illustrated in drawing FIG. 7, depicting resin 24 filling the cavity 10''' of a transfer mold 5''' in a substantially vertical direction to cover at least the second surface 55 of the substrate, in this case a flip-chip type semiconductor die 52. Of course, the cavity 10''' may alternatively be configured to hold and facilitate encapsulation of an individual semiconductor die 52, a plurality of individual dice, or a wafer or other large-scale substrate with a plurality of semiconductor devices thereon. The fourth embodiment is similar to the second embodiment in all respects, except the semiconductor die 52 includes conductive structures 56, such as balls, bumps, pillars, or columns including a conductive material such as a solder, other metal or metal alloy, a conductive epoxy, a conductor-filled epoxy, or a z-axis conductive elastomer, predisposed on and protruding from the bond pads thereof. Additionally, the second half 14''' of the transfer mold 5''' may include a plurality of imperforate recesses 58 formed in and configured to substantially conformally receive at least portions of conductive structures 56 so as to prevent resin 24 from completely covering the same.